



Monte Carlo Study of Thermal Rectification in Nanostructured Asymmetric Boundaries

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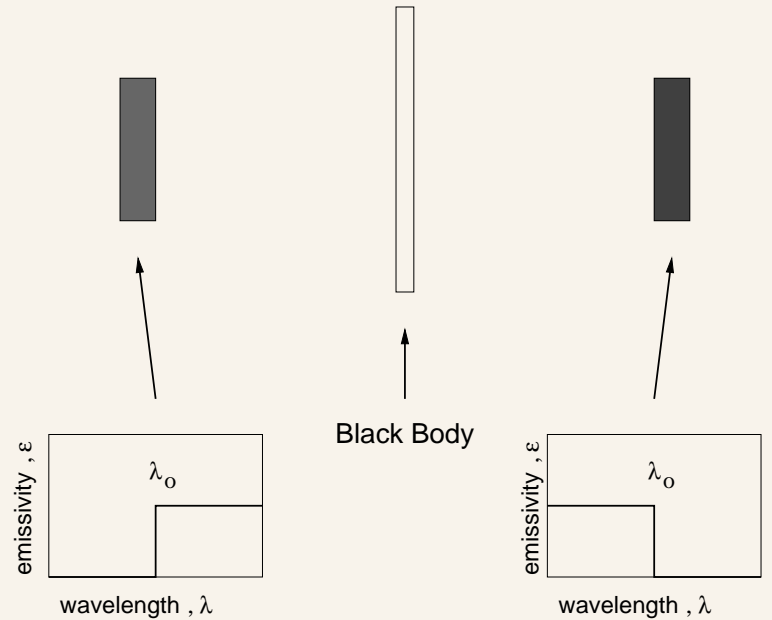
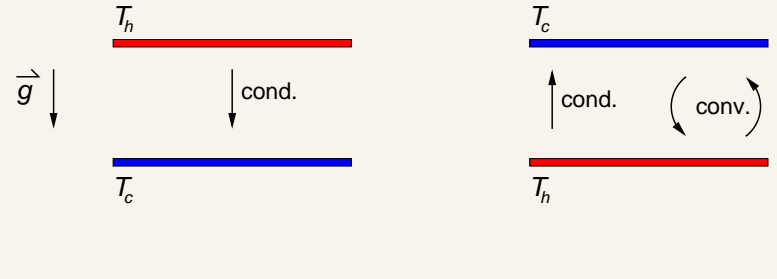
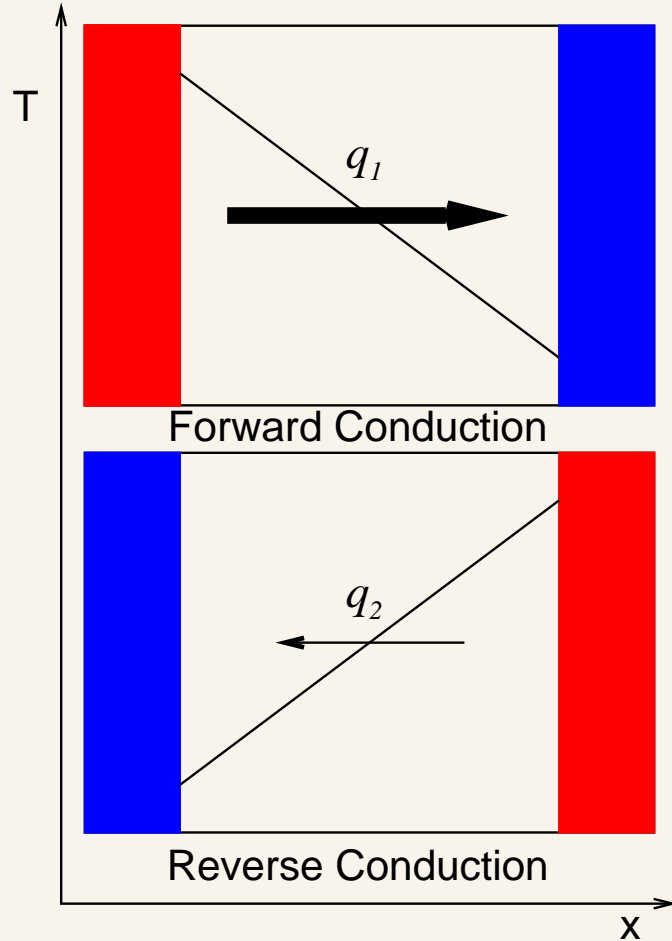
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March 14, 2011

ASME/JSME 8th Thermal Engineering Joint Conference

Funded in part by DARPA Young Faculty Award, 2008

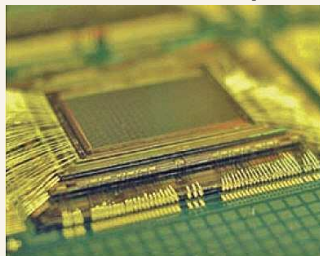
Thermal rectification is a phenomenon where transport through a device is dependent on direction



Smart Thermal Systems



Chip Technology



directindustry.com



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Thermoelectrics



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Portable Electronics



Thermal Barrier Coatings



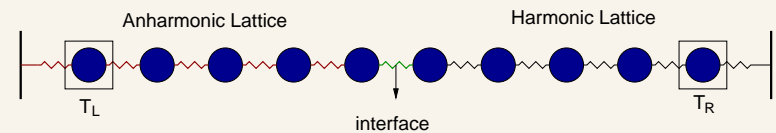
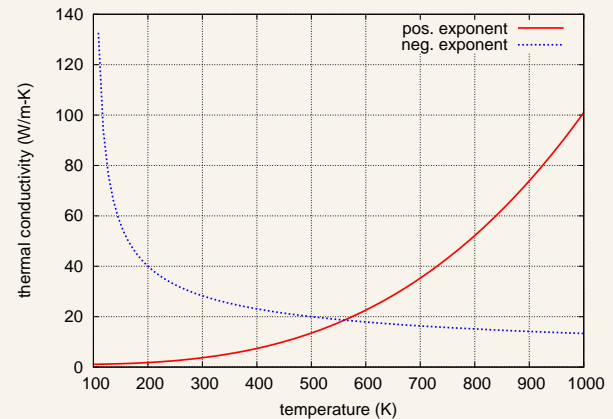
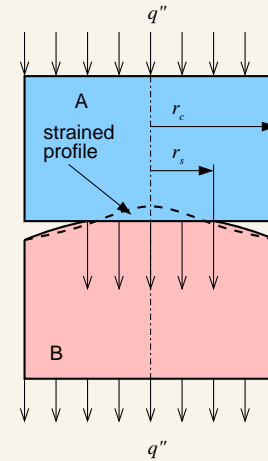
siemens.com

First reported observation was by Starr in 1936

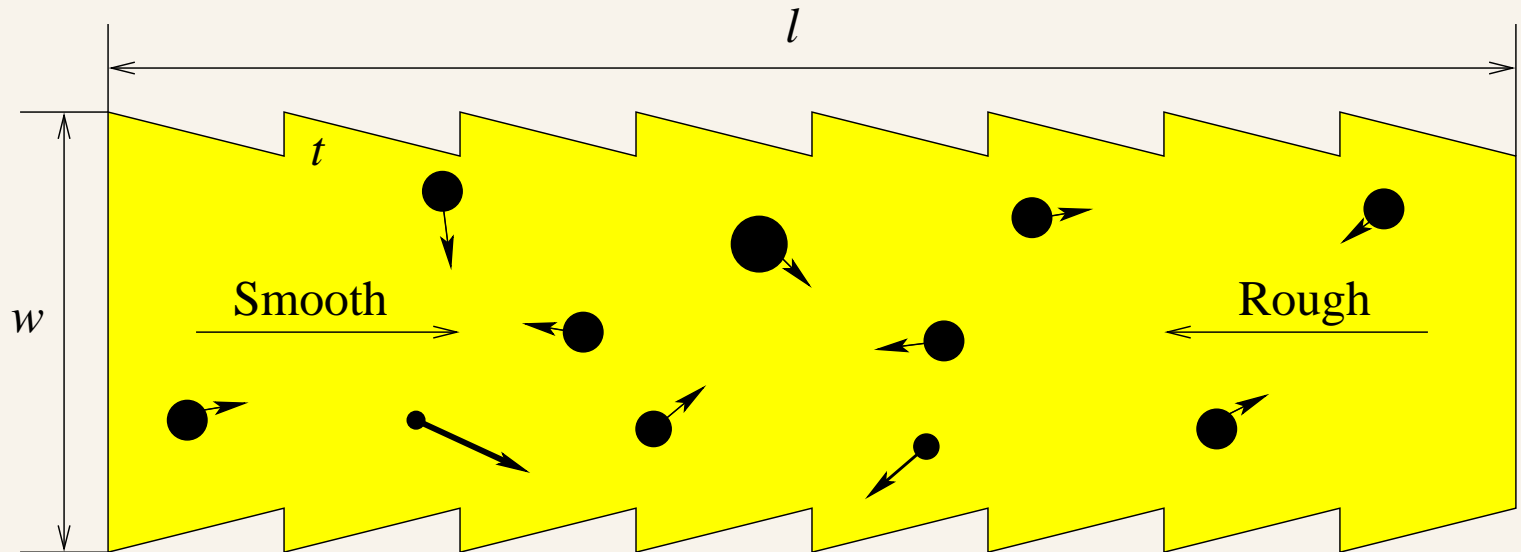
Level of rectification: $\mathcal{E} = \frac{\kappa^+ - \kappa^-}{\kappa^+ + \kappa^-}$

Investigators	System	Mechanism	\mathcal{E}
Starr, 1936	Cu/Cu ₂ O	electronic	0.39
Barzelay, 1955	Al/SS	thermal warping	0.67
Rogers, 1961	Al/SS	thermal potential barrier	0.1
Powell et al., 1962	Al/SS	thermal warping	0
Clausing, 1966	SS/Al	thermal strain	0.2
Lewis and Perkins, 1968	Al/SS	thermal warping	0.41
O'Callaghan et al., 1970	varied	thermal warping	0.13
Stevenson et al., 1991	varied	thermal warping	0.21
Chang et al., 2006	CNT and BNNT	non-uniform mass loading	0.034

- Contact resistance change due to thermal expansion
 - Rogers (1961)
 - Clausing (1966)
 - O'Callaghan (1970)
- Temperature dependence of thermal conductivity
 - Sun et al. (2001)
 - Hu et al. (2006)
 - Dames (2009)
- Nonlinear lattice/potential
 - Terraneo et al. (2002)
 - Li et al. (2004)
 - Segal and Nitzan (2005)
 - Casati (2005)



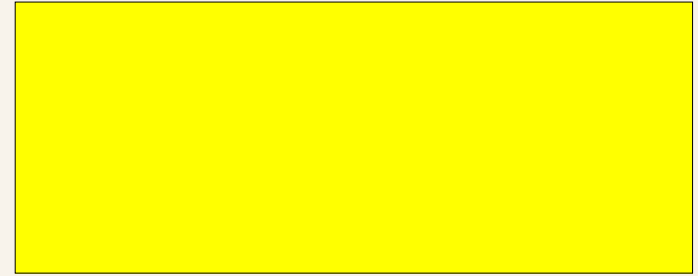
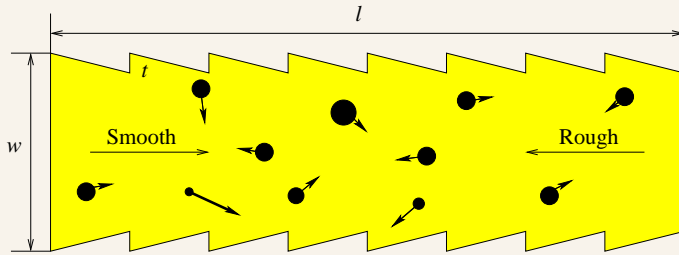
Simulations using Monte Carlo technique



- Initialization
 - Number of phonons initially prescribed ($\geq 100,000$)
 - Randomly distributed throughout the device
 - Polarization and frequency obtained based on initial temperature
 - Momentum calculated from analytic dispersion relation
- Three-phonon scattering is used based on the model and rates from *Holland, Physical Review, 1963*
- Cross sections of 10×10 nm to 1000×1000 nm and lengths of 10 nm to 1000 nm

$$\begin{aligned} \text{Analytic phonon dispersion} &\Rightarrow \omega(k) = \omega_{max,b} \sqrt{\frac{1-\cos ka}{2}} \\ \text{Max. TA and LA frequencies} &\Rightarrow 1.23 \times 10^{13} \text{ Hz}, 4.5 \times 10^{12} \text{ Hz} \\ \text{3-D Density of States} &\Rightarrow D(k) = \frac{k^2}{2\pi^2 V_g} \\ \text{Phonon group velocity} &\Rightarrow V_g = \nabla_k \omega \\ \text{Bose-Einstein distribution} &\Rightarrow \langle n \rangle = \frac{1}{\exp \frac{\hbar\omega}{k_B T} - 1} \end{aligned}$$

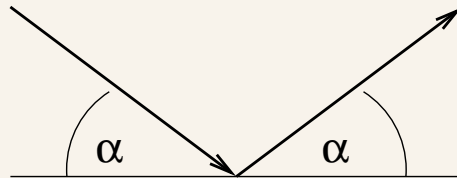
Direction- and Frequency-Dependent Boundaries



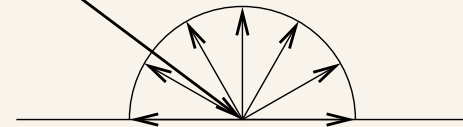
- Boundaries parallel to x-axis have direction and frequency dependence
- If a phonon with negative x-momentum strikes a boundary parallel to the x-axis a parameter, $p(\omega, \eta)$, is calculated based on the phonon frequency and characteristic roughness
- If $p \ll 1$, the phonon has a high probability of a diffuse reflection

$$p(\omega, \eta) = \exp\left[-\frac{64\pi^5 \eta^2 \omega^2}{V_g^2}\right]$$

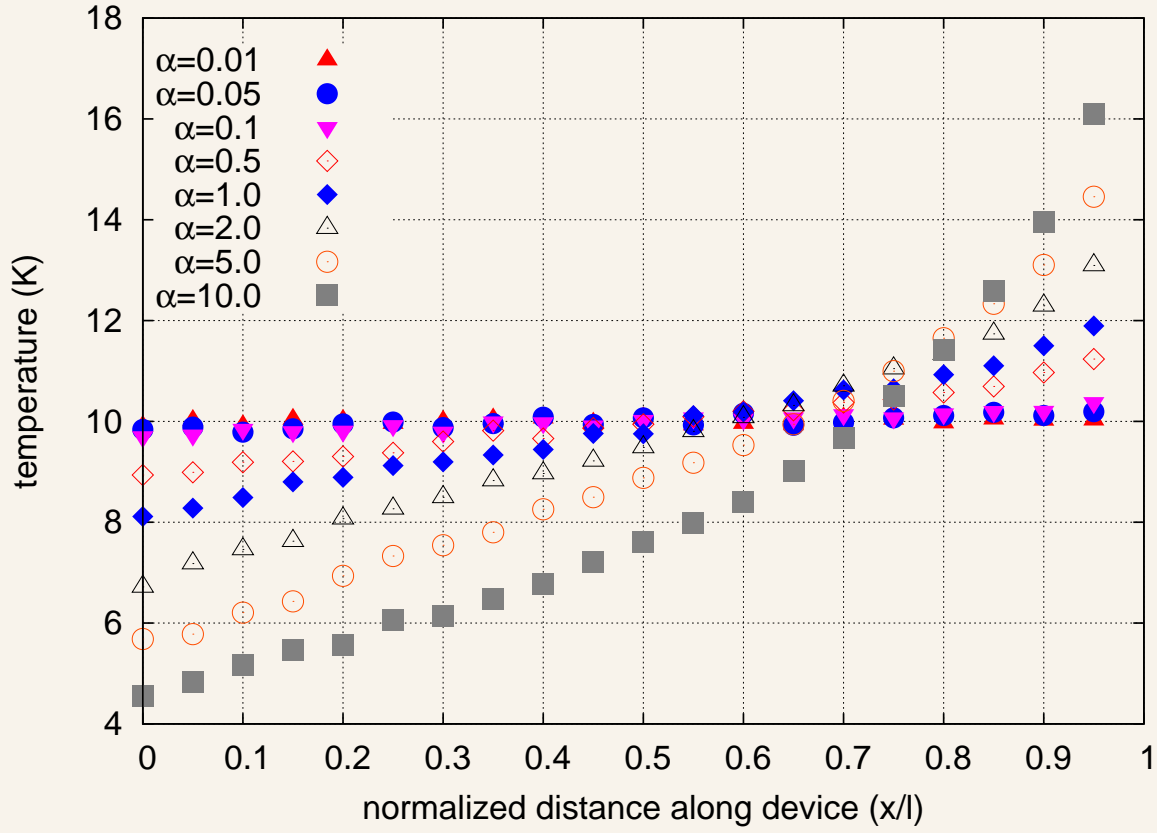
Ziman, Electrons and Phonons, 1960



Specular Reflection

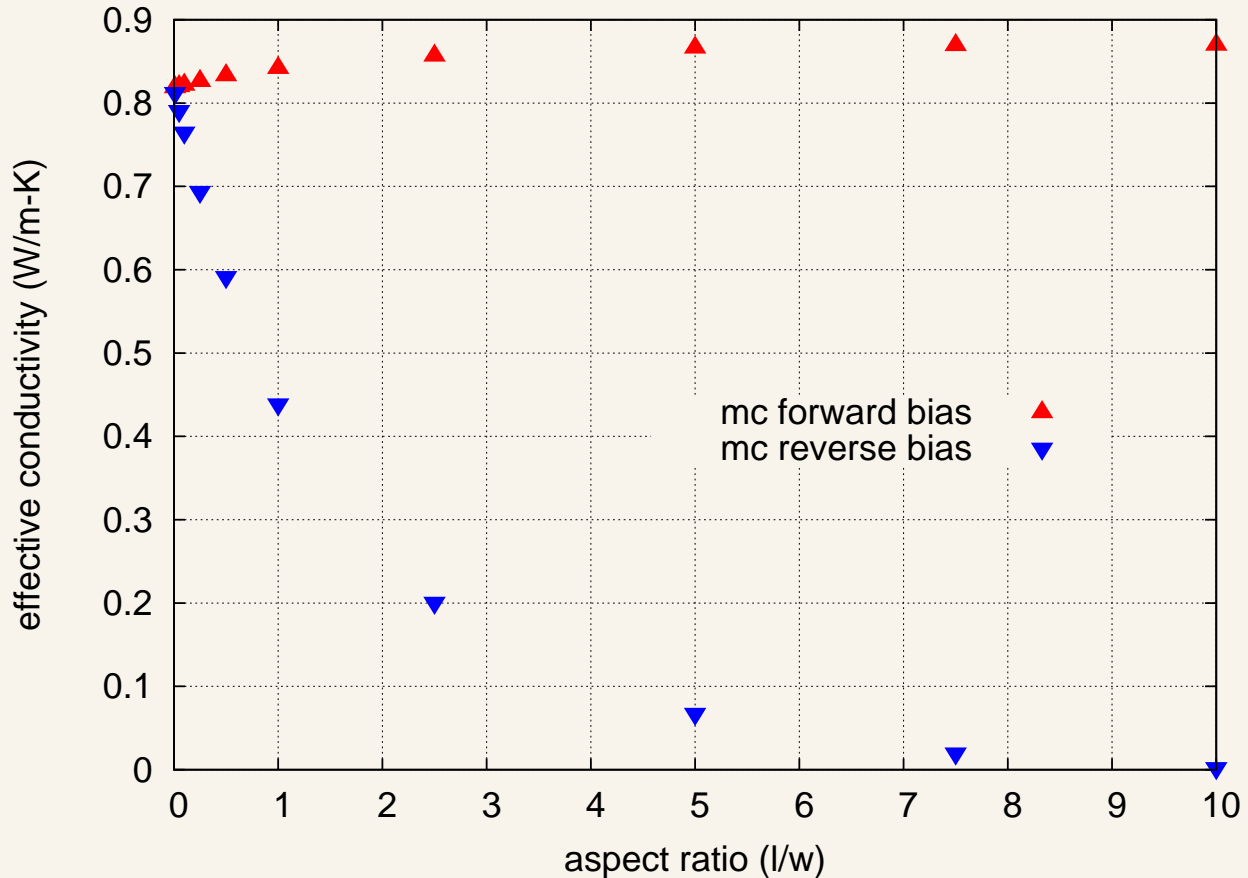


Diffuse Reflection

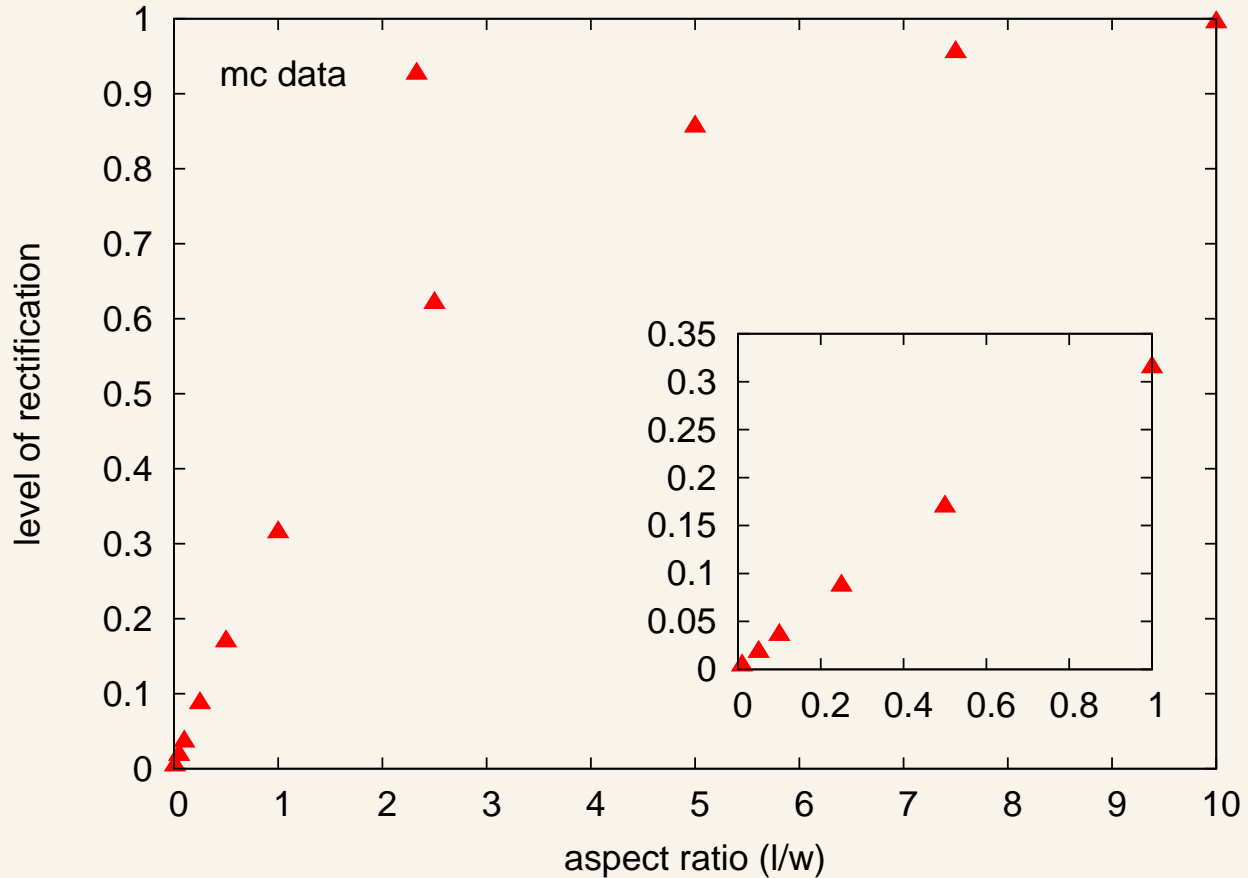


$$\alpha = l/w$$

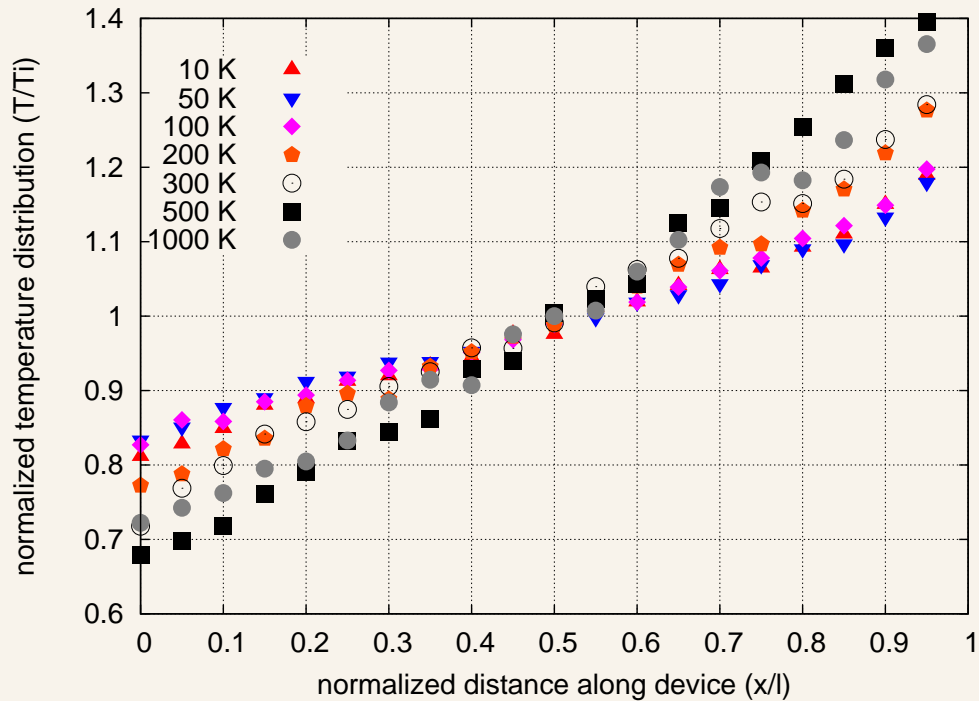
- Boundaries are insulated, so the device is self-biasing.



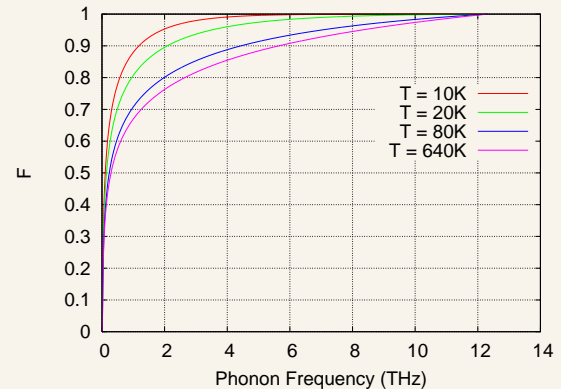
- For a biased device, the amount of transport is calculated so thermal conductivity can be deduced.

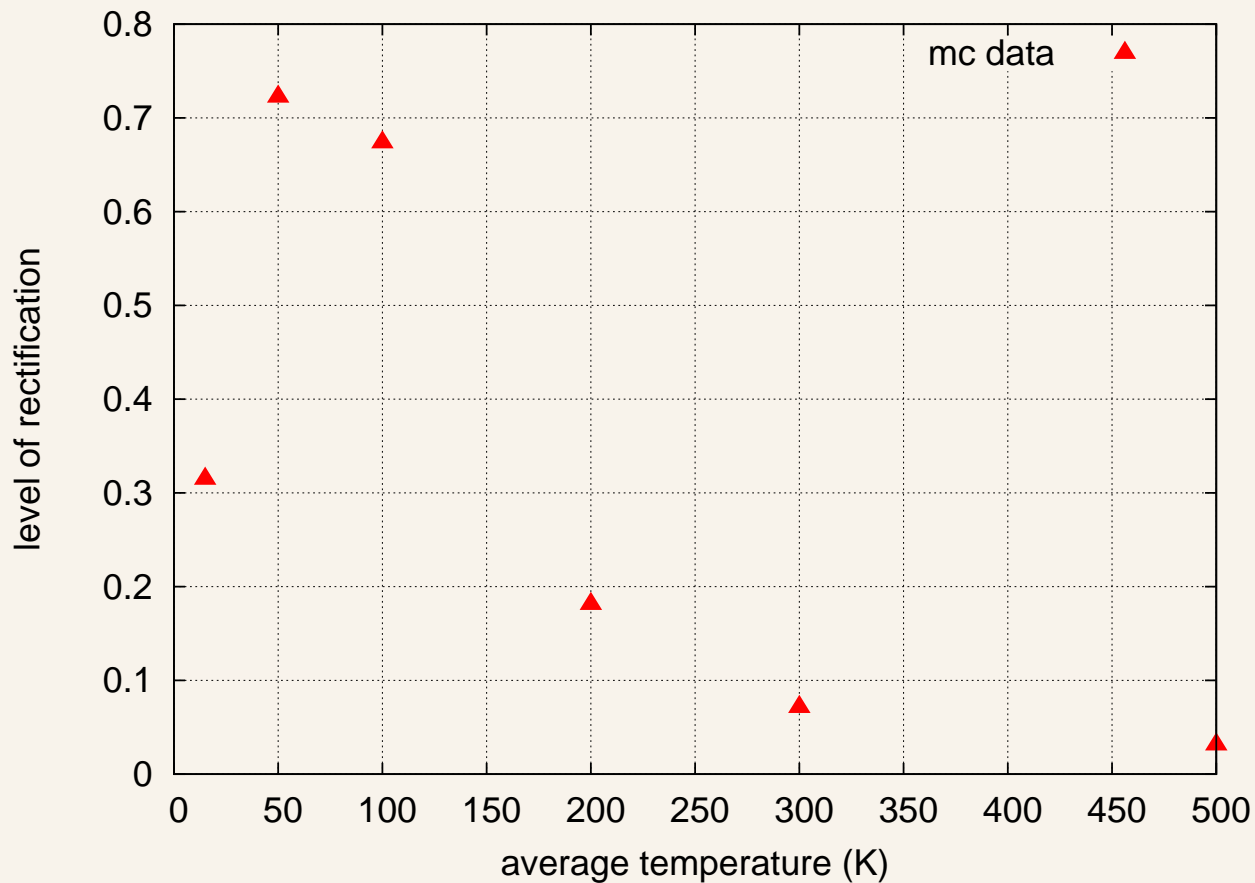


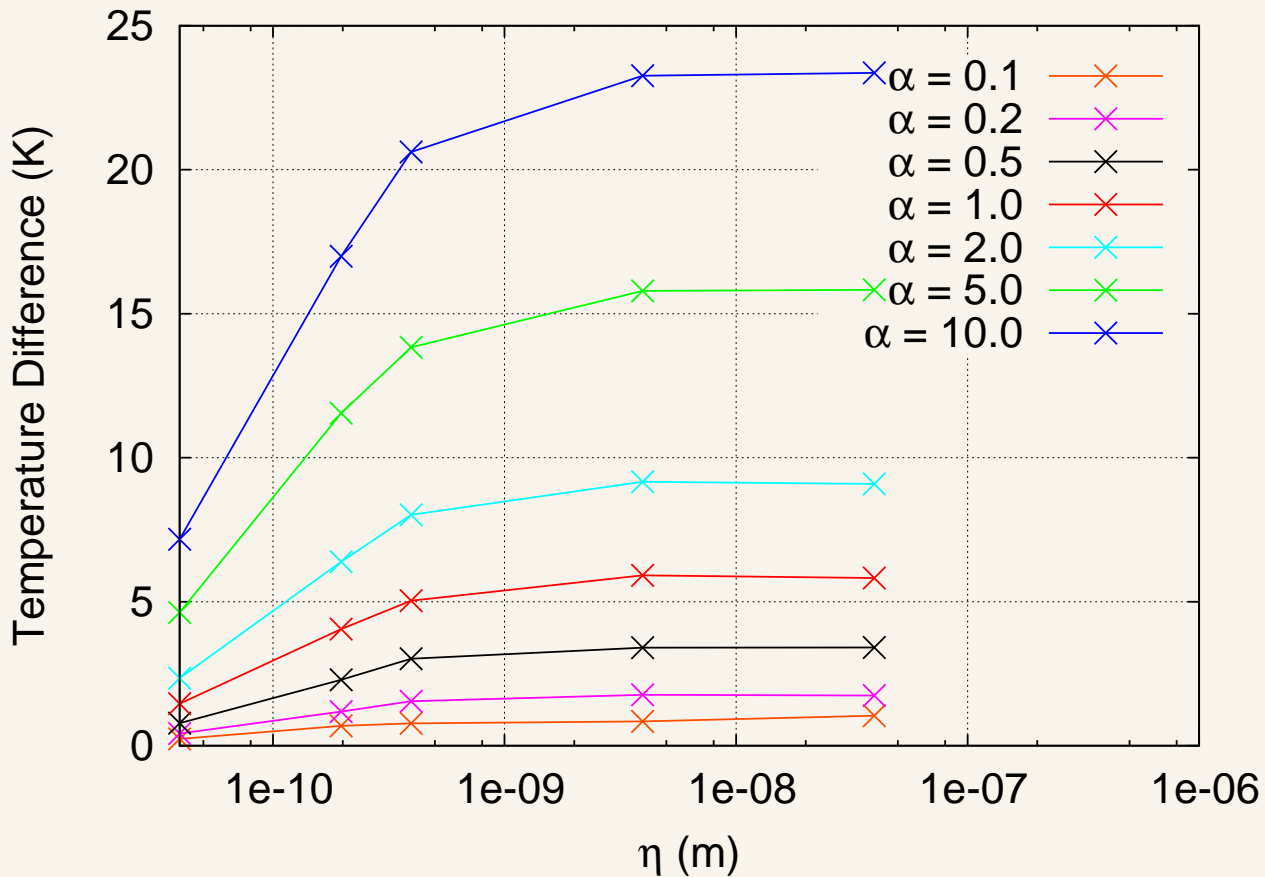
- boundary dominated devices show large amounts of rectification
- $\varepsilon = 1$ means no transport in unfavorable direction



$$F(\omega) = \sum_b \frac{\int_0^\omega \langle n \rangle D(\omega) d\omega}{\int_0^{\omega_{\max,b}} \langle n \rangle D(\omega) d\omega}$$







- Rectification can be increased by
 - large aspect ratio devices
 - selecting a temperature that gives a distribution of phonons, but does not introduce too much scattering
 - designing a roughness that is of the order of the dominant phonon wavelength
- Fabrication is extremely difficult due to boundary requirements

